

### EASRR3216WA2

#### Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.

#### Descriptions

- The EASRR3216WA2 SMD LED is much smaller than lead frame type components, thus enables smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

#### Applications

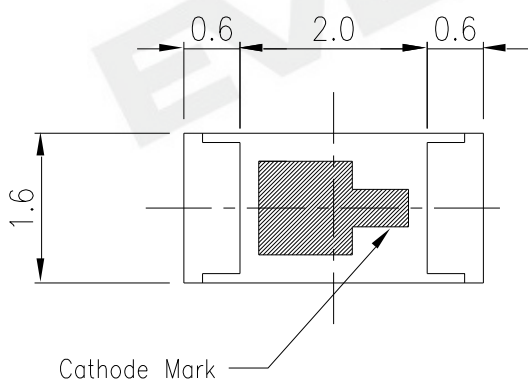
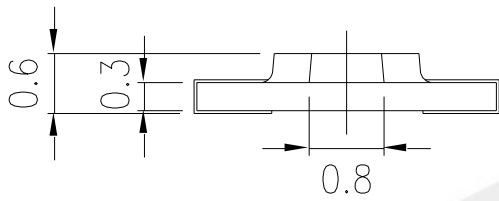
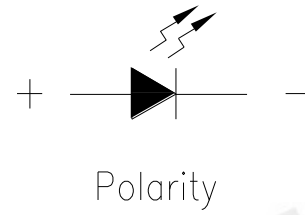
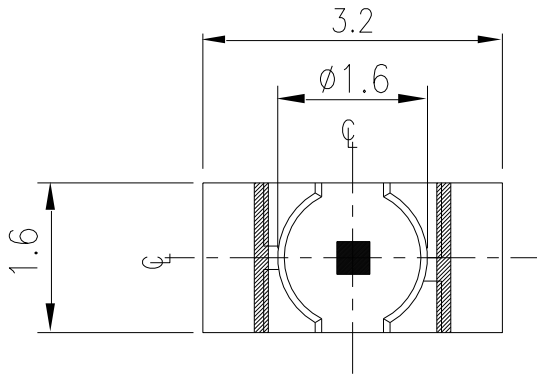
- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

### Device Selection Guide

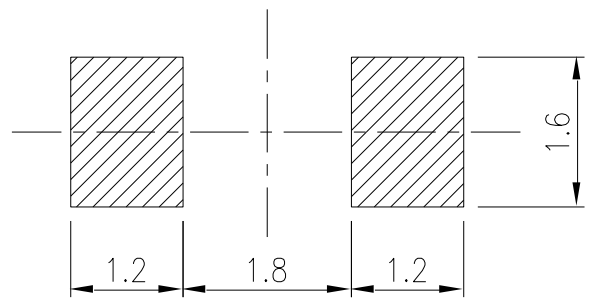
Part No.	Chip		Resin Color
	Material	Emitted Color	
EASRR3216WA2	InGaN	Pure White	Yellow Diffused

EVERLIGHT

### Package Outline Dimensions



Recommend Soldering Pad



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

**Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	100	mA
Power Dissipation	P <sub>d</sub>	95	mW
Electrostatic Discharge	ESD	150	V
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

**Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	36.0	-----	90.0	mcd	I <sub>F</sub> =2mA
Viewing Angle	2θ 1/2	-----	140	-----	deg	
Forward Voltage	V <sub>F</sub>	2.60	-----	3.00	V	
Reverse Current	I <sub>R</sub>	-----	-----	50	μA	V <sub>R</sub> =5V

**Bin Range Of Luminous Intensity & Forward Voltage**

Symbol	Bin Code	Min.	Max.	Unit	Condition
I <sub>v</sub>	N2	36.0	45.0	mcd	I <sub>F</sub> =2mA
	P1	45.0	57.0		
	P2	57.0	72.0		
	Q1	72.0	90.0		
V <sub>F</sub>	28	2.60	2.70	V	
	29	2.70	2.80		
	30	2.80	2.90		
	31	2.90	3.00		

**Note:**

**1:Tolerance of Luminous Intensity ±11%**

**2:Tolerance of Forward Voltage ±0.1V**

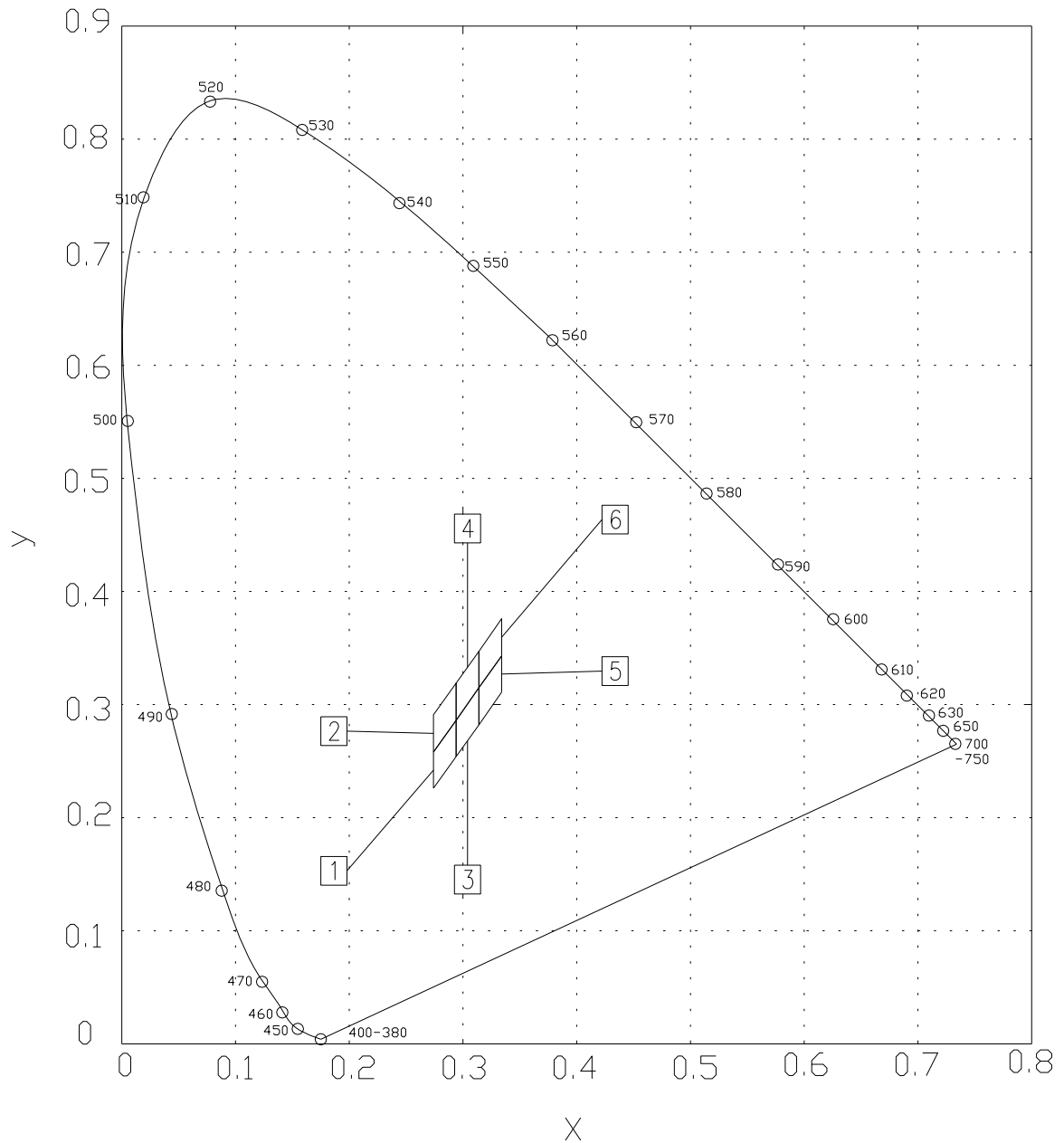
### Chromaticity Coordinates Specifications for Bin Grading

Group	Bin Code	CIE_x	CIE_y	Condition
A	1	0.274	0.226	If=2mA
		0.274	0.258	
		0.294	0.286	
		0.294	0.254	
	2	0.274	0.258	
		0.274	0.291	
		0.294	0.319	
		0.294	0.286	
	3	0.294	0.254	
		0.294	0.286	
		0.314	0.315	
		0.314	0.282	
	4	0.294	0.286	
		0.294	0.319	
		0.314	0.347	
		0.314	0.315	
	5	0.314	0.282	
		0.314	0.315	
		0.334	0.343	
		0.334	0.311	
6	0.314	0.315		
	0.314	0.347		
	0.334	0.376		
	0.334	0.343		

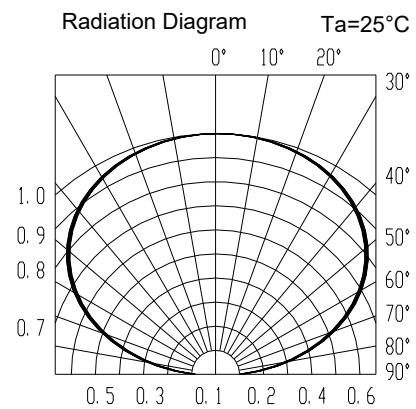
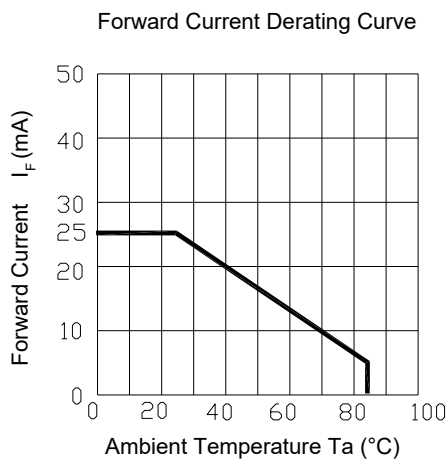
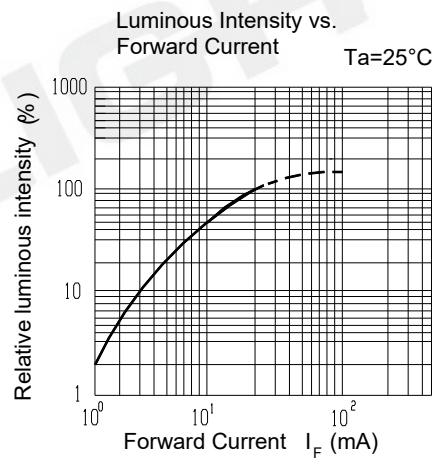
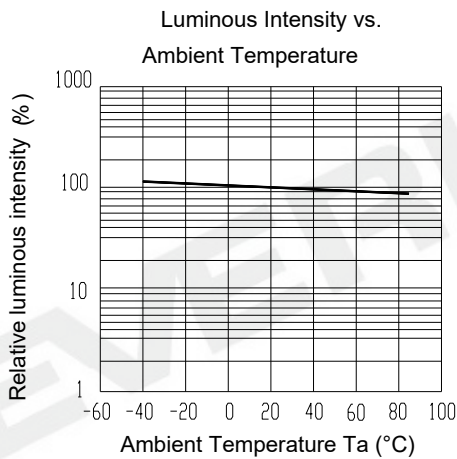
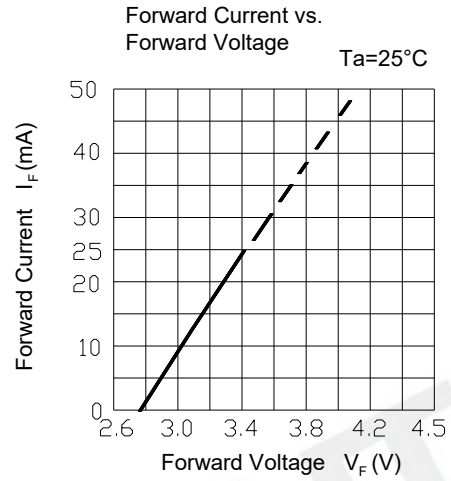
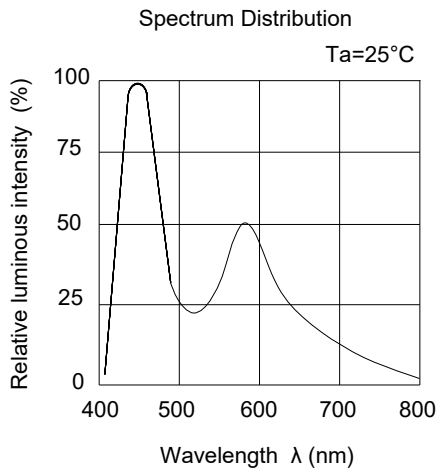
**Notes:**

- 1.The C.I.E. 1931 chromaticity diagram ( Tolerance  $\pm 0.01$ ).
- 2.The products are sensitive to static electricity and care must be fully taken when handling products.

## CIE Chromaticity Diagram



## Typical Electro-Optical Characteristics Curves





### Label Explanation

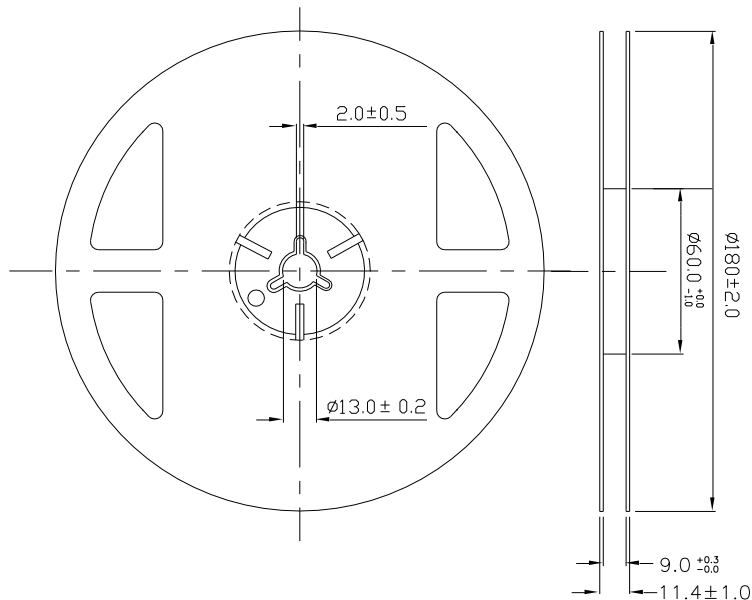
**CAT:** Luminous Intensity Rank

**HUE:** Chromaticity Coordinates

**REF:** Forward Voltage Rank

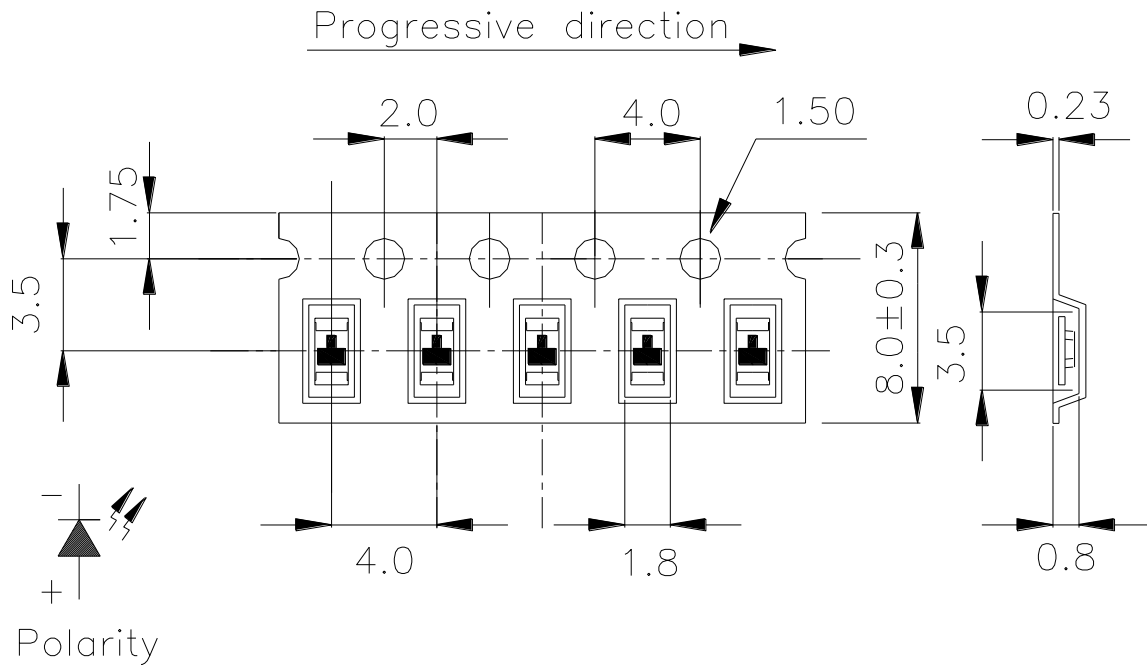


### Reel Dimensions



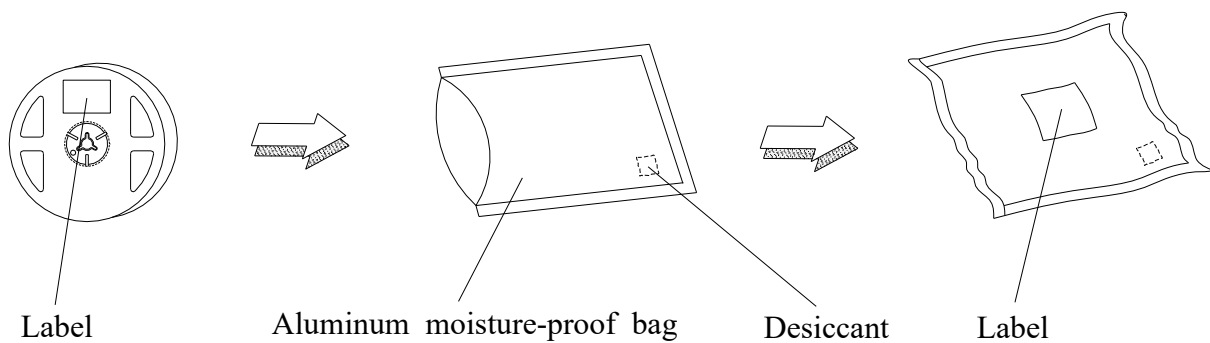
**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  ,Unit = mm

**Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel**



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$ , Unit = mm

**Moisture Resistant Packaging**



### Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Max. 10sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	IF = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

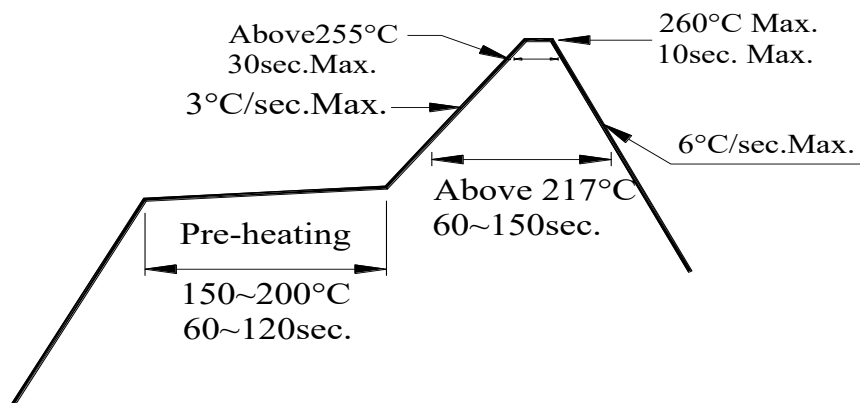
2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

#### 4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

